

Launch Date:

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*An Industry-Academia
Consortium*

NanoPack

Nano Materials,
Components, Packaging
and Systems



**MICROSYSTEMS
PACKAGING
RESEARCH
CENTER**

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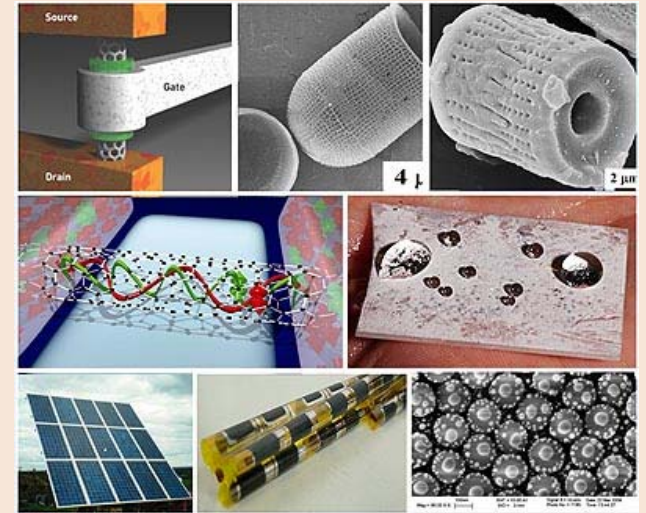
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Focus:

Nano-science and technology has been a buzzword for about five years. Most of the research to date in this area, however, has been focused either in materials or devices. Such technologies as carbon nano tubes (CNTs), molecular self assembly and manufacturing, nano imprints and sensors, etc. are being explored and studied for mechanical, physical, chemical, photonic, electronic and biological properties.

The Packaging Research Center proposes to go beyond nano-materials and devices to form chip-to package interconnects, system level components, sensors, dielectrics, coatings and batteries, leading to nano-modules. This proposed emphasis is expected to lead to a number of commercial applications, not achieved so far.

To accomplish these goals, the Packaging Research Center proposes a global Industry-Academia consortium on "Nano Packaging, Components, and Systems (NanoPack)" to explore a variety of new opportunities that these materials may provide.

**Proposed Projects:**

- Nano-embedded Thin Film Passive Components
- Nano-capacitors and Batteries
- Modeling and Characterization
- Nano-materials for Batteries
- Embedded Thin film Processes for Batteries in Organic Packages
- Nano Materials for Thermal and Electrical Interconnects
- Nano Surfaces for High Performance Reliability Electronic and Photonic Packaging

Research Tasks:

- Chip-to-Package Nano Interconnections
- Nano-coatings
- Nano-sensor

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